

Product Change Notification - KSRA-10KDPB147 (Printer Friendly)

Date:

24 Apr 2017

Product Category:**Notification subject:**

CCB 2909 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 160K wafer technology available in 20L QFN package at NSEB assembly site

Notification text:**PCN Status:**

Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 160K wafer technology available in 20L QFN package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T and 8600 die attach and G770HCD and G700LTD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	NSEB Assembly Site		NSEB Assembly Site
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600

Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	EFTEC-64T		EFTEC-64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

September 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	April 2017						→	September 2017				
Workweek	13	14	15	16	17	18		35	36	37	38	39
Initial PCN Issue Date					X							
Qual Report Availability												X
Final PCN Issue Date												X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

April 24, 2016: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-10KDPB147_Affected CPN.pdf](#)

[PCN_KSRA-10KDPB147_Qual Plan.pdf](#)

[PCN_KSRA-10KDPB147_Affected CPN.xlsx](#)

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